

## 2SD1820G

## Silicon NPN epitaxial planar type

For general amplification Complementary to 2SB1219G

#### ■ Features

- ullet Low collector-emitter saturation voltage  $V_{CE(sat)}$
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	60	V	
Collector-emitter voltage (Base open)	$V_{CEO}$	50	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V	
Collector current	$I_{C}$	500	mA	
Peak collector current	$I_{CP}$	1	A	
Collector power dissipation	$P_{C}$	150	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

#### Package

- CodeSMini3-F2
- Marking Symbol: X
- Pin Name
  - 1: Base
  - 2: Emitter
  - 3: Collector

### ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = 10  \mu \text{A},  I_{\rm E} = 0$	60	· Vic	*	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 2 \text{ mA}, I_B = 0$	50	80,		V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10  \mu A, I_C = 0$	5	0		V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_{E} = 0$	1.00		0.1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub> *2	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 150 mA	85		340	_
	h <sub>FE2</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 500 \text{ mA}$	40			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.35	0.60	V
Transition frequency *1	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		6	15	pF
(Common base, input open circuited)						

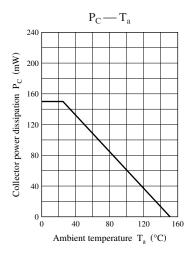
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

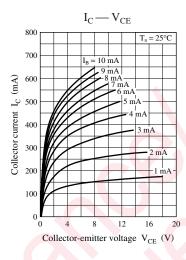
<sup>\*2:</sup> Rank classification

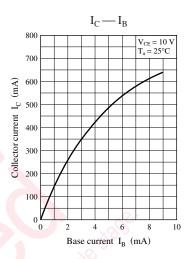
Rank	Q	R	S	No-rank
$h_{FE1}$	85 to 170	120 to 240	170 to 340	85 to 340
Marking symbol	XQ	XR	XS	X

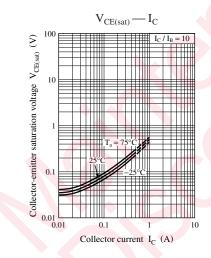
Product of no-rank is not classified and have no marking symbol for rank.

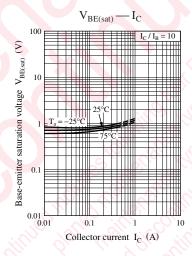
<sup>2. \*1:</sup> Pulse measurement

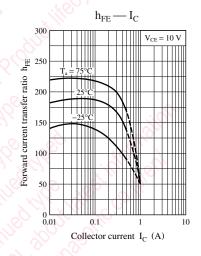


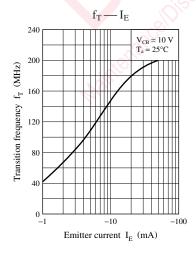


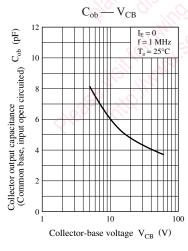


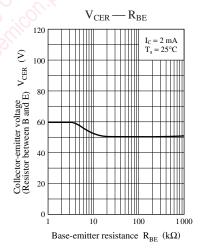




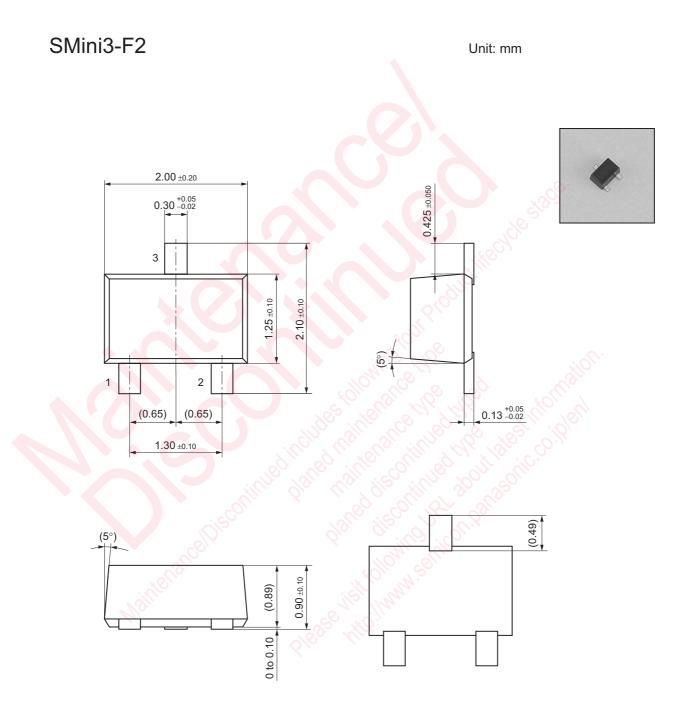








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